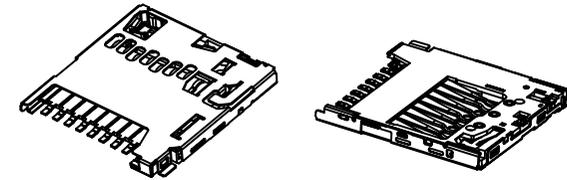
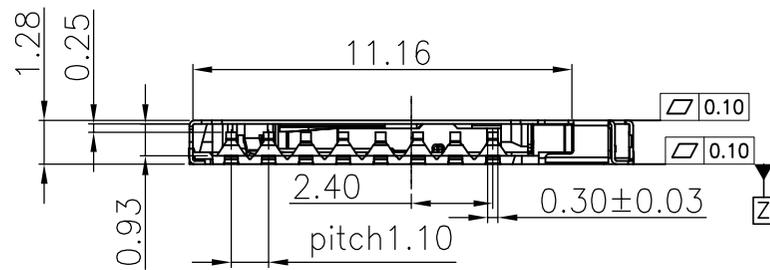
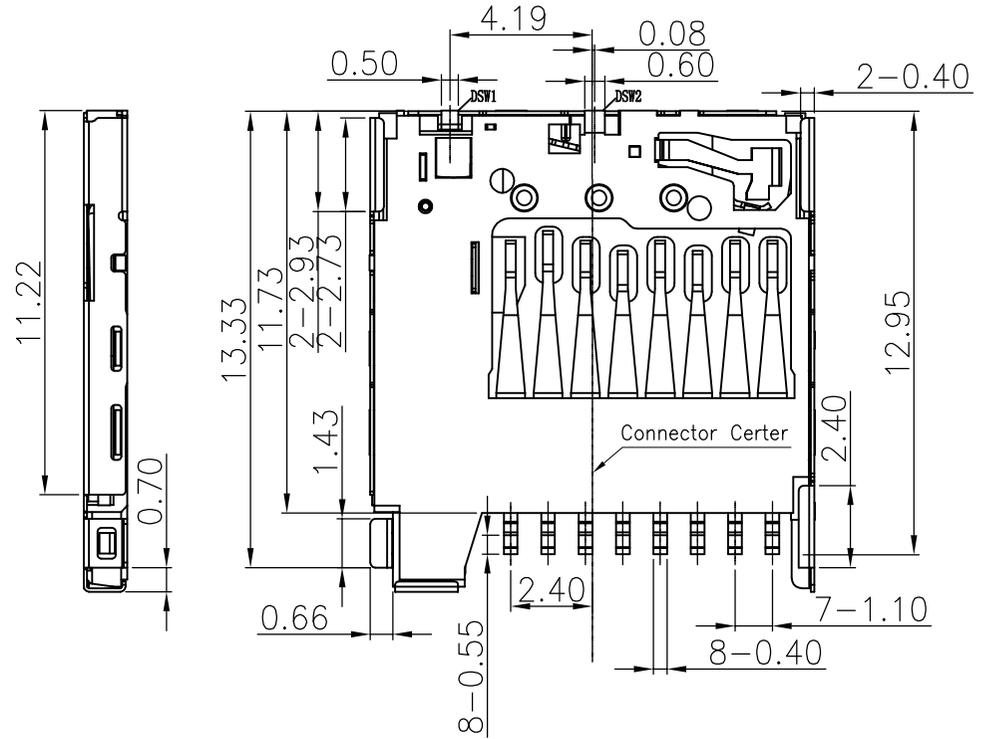
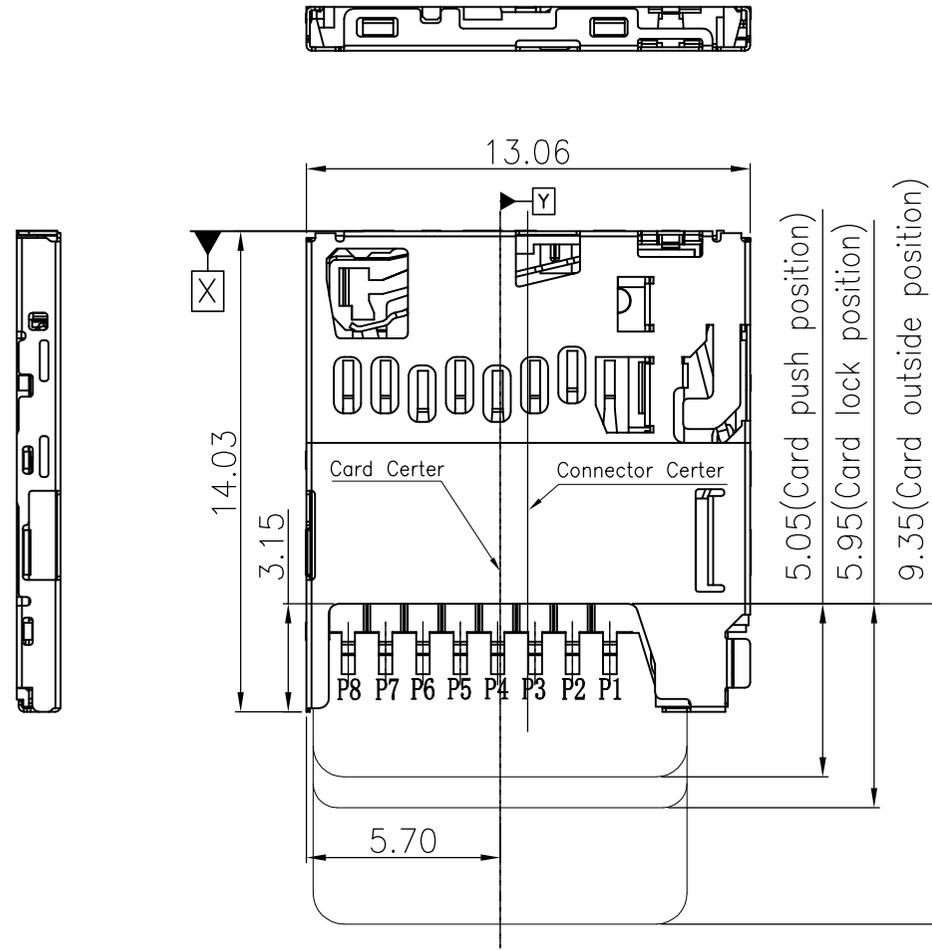
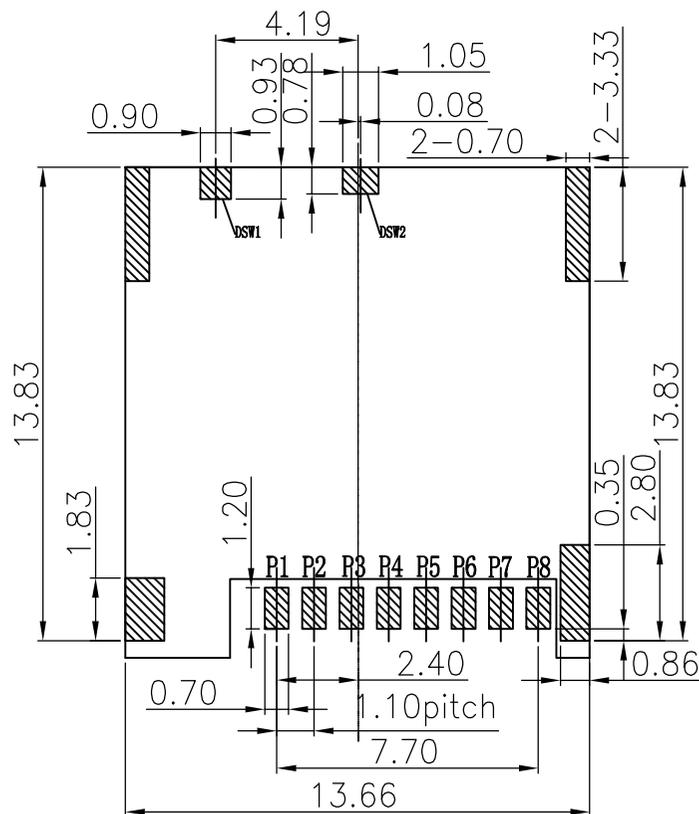


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



GENERAL TOLERANCE		DWG NO.	JYSA0525-010	APPD:	RALINY	Scale	1:1
X.±0.45	x.'±5'	Title	MICRO SD PUSH CONN 1.28H 内焊式	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-TF128-054	Date	2012/02/29		
.XXX±0.15	.xxx'±0.5'	杰宇森电子有限公司 JIE YU SEN ELECTRONIC CO., LTD.					
SHEET	1/2						

REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2011/10/31



RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)

- PAD AREA
- KEEP OUT AREA
- GND PATTERN ONLY

PIN NO.	PIN ASSIGNMENT
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1

Specification

1.MATERIAL:

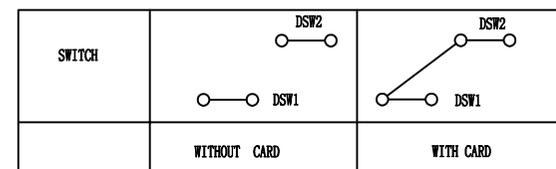
- 1.1 Insulator: High Temperature Thermoplastic, LCP SZ6505 black 94V-0.
- 1.2 Contact: Beryllium copper(7035-TM06, T=0.15mm)
- 1.3 Shell: SUS301-3/4H T=0.10mm

2.Plating:

- 2.1 Contact: Plated 80u"min Ni Overall
Plated 1u"min Au Selective contact area
Selective 1u"min AU over Ni on solder area
- 2.2 Shell: Solder tail Plated 1u"min AU overll 50u"min Ni

3.Property:

- 3.1 Current Rating :0.5A AC/DC max.
- 3.2 Voltage Rating :12V AC/DC
- 3.3 Ambient Temperature Range :-20°C~+60°C
- 3.4 Ambient Humidity Range :95% R.H. Max.
- 3.5 Contact Resistance:100mΩ max.
- 3.6 Insulation Resistance:1000MΩ min./500VDC
- 3.7 Durability:5,000 cycles



GENERAL TOLERANCE		DWG NO.	JYSA0525-010	APPD:	RALINY	Scale	1:1
X. ± 0.45	x. $\pm 5^{\circ}$	Title	MICRO SD PUSH CONN 1.28H 内焊式	CHKD:		UNIT	mm
.X ± 0.35	.x $\pm 2^{\circ}$			DR:			
.XX ± 0.25	.xx $\pm 1^{\circ}$	Part No.	JYS-TF128-054	Date	2012/02/29		
.XXX ± 0.15	.xxx $\pm 0.5^{\circ}$						
SHEET	2/2			杰宇森电子有限公司 JIE YU SEN ELECTRONIC CO.,LTD.			